



ELEN E3106/4106 Lecture 14

p-n Junction Breakdown and Narrow Base Diodes Outline

- Zener breakdown
- Avalanche breakdown
- Punch-through breakdown
- Narrow—base diodes

Assignments:

Reading: Streetman and Banerjee §5.4
Homework 6 due Friday Oct. 24th by 5pm
Exam 2 Tuesday Oct. 28th

Recap of p-n Junctions

- We've (nearly) exhausted the p-n junction. Now we know:
 - 1) Why and how it conducts current (forward ^{E_0} , reverse)
 - 2) How to calculate depletion width W , field, built-in voltage V_0
 - 4) How diodes store charge as capacitors in RB (we have not discussed FB capacitance)
 - 5) How to make optoelectronics based on photodiodes (solar cells, photodetectors, LEDs & lasers)
- Today, we have 2 final topics before we get to BJTs!
 - 6) How diodes break down
 - 7) Narrow-base diodes

Reverse-bias Breakdown

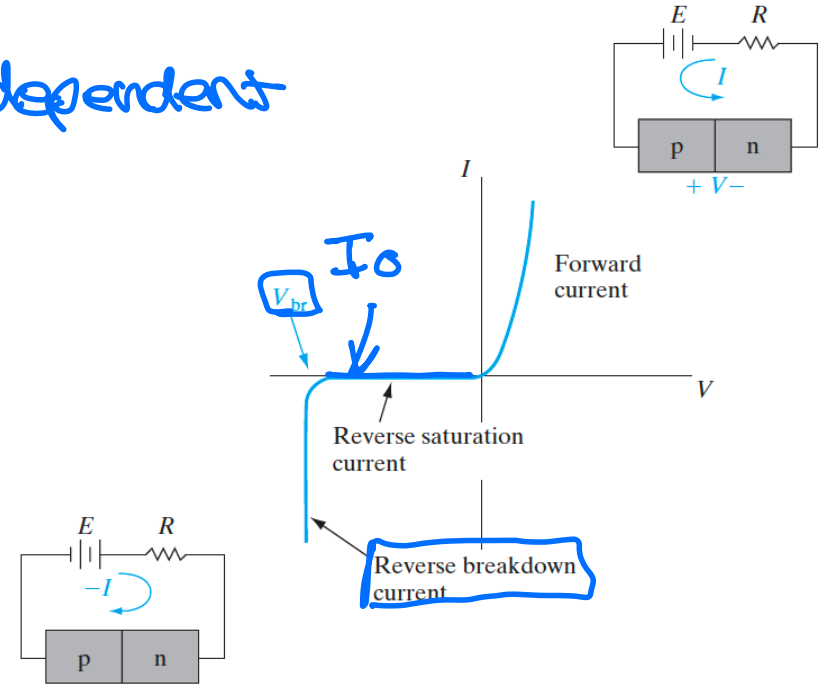
- Recall: so far we have found that p-n junction in RB has a small, essentially voltage-independent reverse saturation current, I_0

- This is true until we reach a critical high reverse bias point, called the breakdown voltage (V_{br})

- We can vary V_{br} through choice of doping concentrations

- What happens at V_{br} ? Reverse current sharply increase, and relatively large currents can flow with little increase in RB

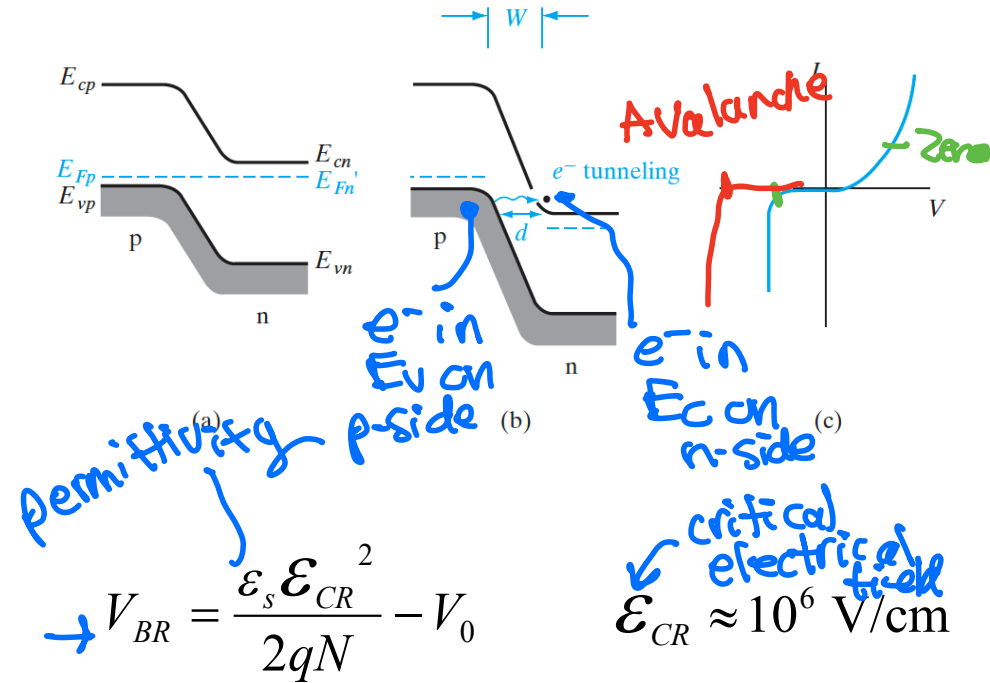
- Is breakdown reversible? In general, yes. Destructive if overheating occurs



Zener Breakdown

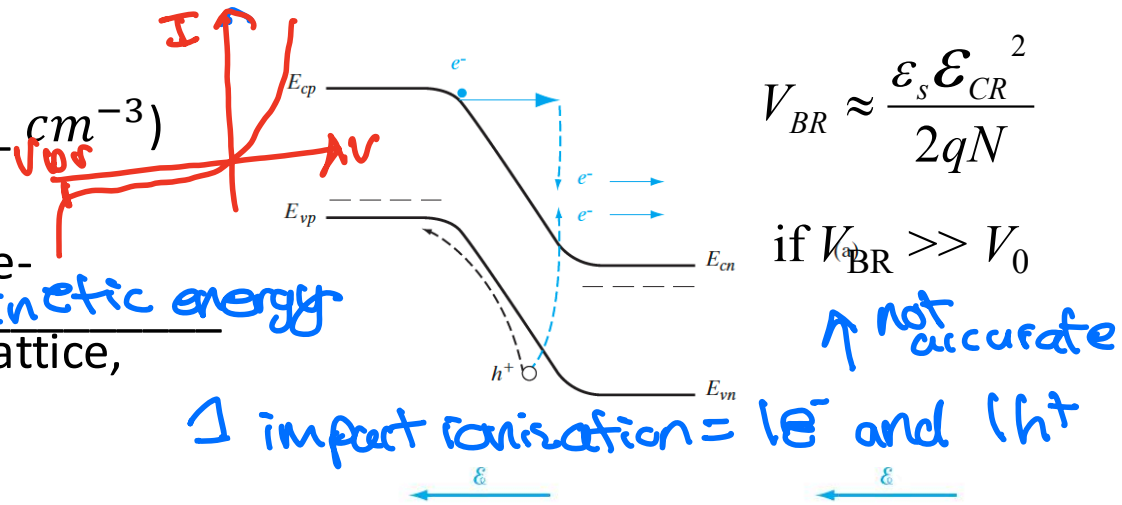
- Dominant for heavily doped junctions ($> 10^{18} \text{ cm}^{-3}$)
- Dominant at low RB (up to a few volts)
- With narrow barrier in RB, tunneling of e- from p-side filled states in E_v to n-side empty states in E_c can occur
- Tunneling distance d becomes smaller with RB as E-field creates steeper slope for band edges
- Prevalent in heavily doped p^+-n^+ junction
 - W must only extend very short into each side of junction
 - We are assuming W does not increase very much with RB so d can become small (accurate for low RB and heavy doping on both sides)

(a) Heavily doped junction at equilibrium, (b) reverse bias with e-tunneling from p to n, (c) I-V characteristic



Avalanche Breakdown

- Dominant for more lightly doped ($< 10^{18} \text{ cm}^{-3}$) junctions
- Because the depletion region is wide, e- accelerated across it will gain enough kinetic energy to cause an ionizing collision with the lattice, generating EHP
 - Called impact ionization
- The original e- and newly generated e- are both swept to n-side, while h+ is swept to p-side --> carrier multiplication
- Multiplication can become high if there are many impact ionization events: imagine incoming e-generated EHP, each of these carriers created additional EHPs through impact ionization, and so on
- This avalanche process causes reverse current to increase

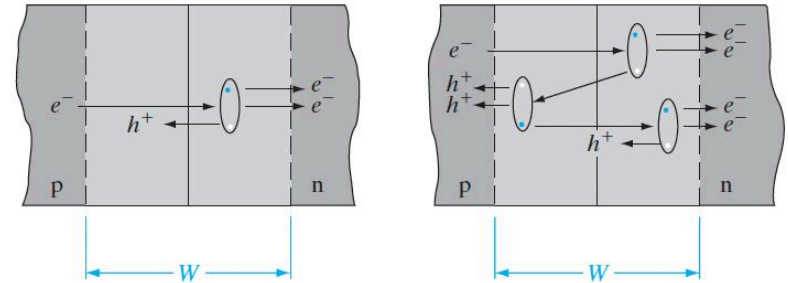


$$V_{BR} \approx \frac{\epsilon_s \mathcal{E}_{CR}^2}{2qN}$$

$$\text{if } V_{BR} \gg V_0$$

↑ not accurate

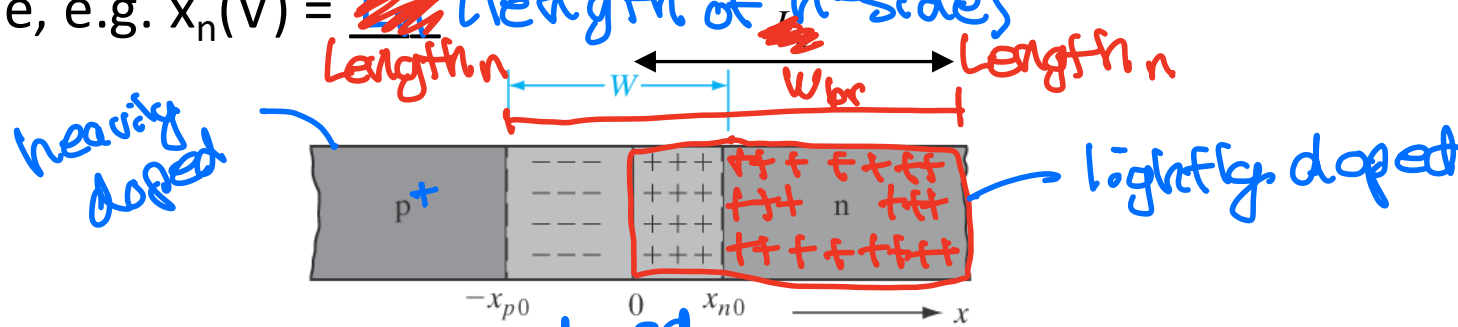
1 impact ionization = 1e- and 1h+



(a) EHPs created by impact ionization, (b) band diagram showing primary e- gaining KE in depletion region, creating secondary EHPs (c) Primary, secondary, and tertiary collisions

Punch-through Breakdown

- Occurs when either depletion region “punches through” the entire length of the diode, e.g. $x_n(V) =$ ~~length of n-side~~



- An issue for short, lightly doped regions
 - Recall: W extends primarily into lightly doped side, as W increases with RB ($\propto \sqrt{V}$) it can fill the entire length!

$$\propto \sqrt{V}$$

$$W = x_n + x_p = \sqrt{\frac{2\epsilon_s}{q} \left(\frac{1}{N_A} + \frac{1}{N_D} \right) (V_0 - V)}$$

- Result: Breakdown below the value of V_{br} predicted by zener or avalanche breakdown

Empirical Observations on Breakdown

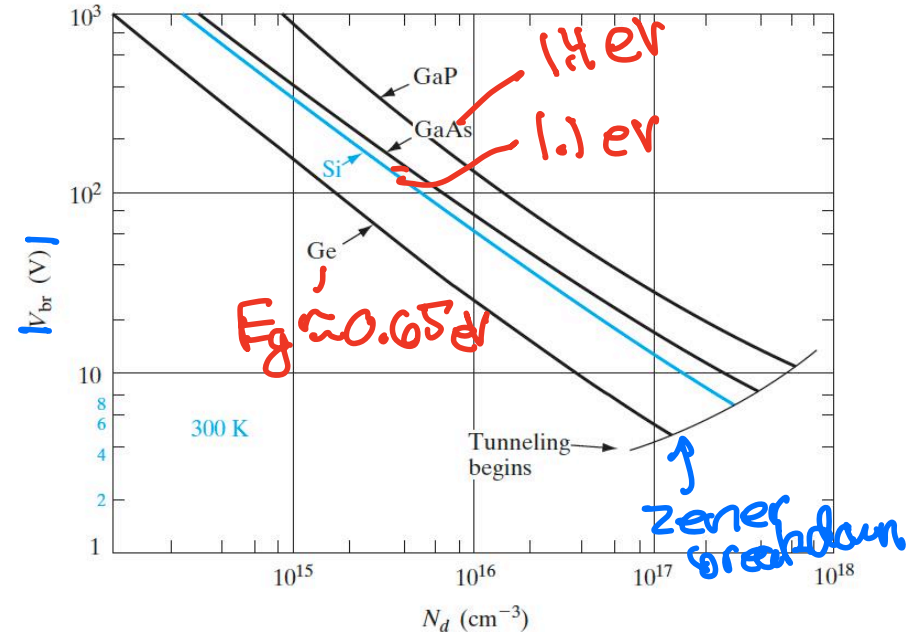
- V_{br} decreases with increased doping, N
- V_{br} decreases with decreasing E_g

What about temperature?

- For tunneling (Zener) breakdown, $|V_{br}| \sim$ decrease minimally with increasing temperature

- For avalanche breakdown,

$|V_{br}| \sim$ increases w/ increasing temperature
→ carriers are scattered before gaining enough K.E. to impact ionize



Problem: Avalanche breakdown

A Ge p+n junction diode has donor doping of $2 \times 10^{15} \text{ cm}^{-3}$ and relative permittivity 16. What will be the minimum thickness of n region that will ensure avalanche breakdown at 300 V reverse bias voltage?

$$\underline{N_d = 2 \times 10^{15} \text{ cm}^{-3}}$$

$$x_{n0} = \frac{W}{1 + \frac{N_d}{N_a}}$$

For p+n junction, $N_a \gg N_d$, so $\frac{N_d}{N_a} \ll 1$ and $1 + \frac{N_d}{N_a} \approx 1$ so $x_{n0} \approx \underline{W}$

$$\underline{W} = \sqrt{\frac{2\epsilon}{q} \left(\frac{1}{N_a} + \frac{1}{N_d} \right) (V_0 - V)} \approx \sqrt{\frac{2\epsilon}{q} \left(\frac{1}{N_d} \right) (V_{br})}$$

* V_0 is very small so we ignore it.

$$x_{n0} \approx \underline{W} = \sqrt{\frac{2(\overset{\approx \epsilon_0}{16})(8.85 \times 10^{-14})}{(1.6 \times 10^{-19})} \left(\frac{1}{2 \times 10^{15}} \right) (\underline{300V})}$$

$$x_{n0} = \underline{16.3 \text{ microns}}$$

This is the minimum thickness that will ensure avalanche breakdown rather than punch-through.

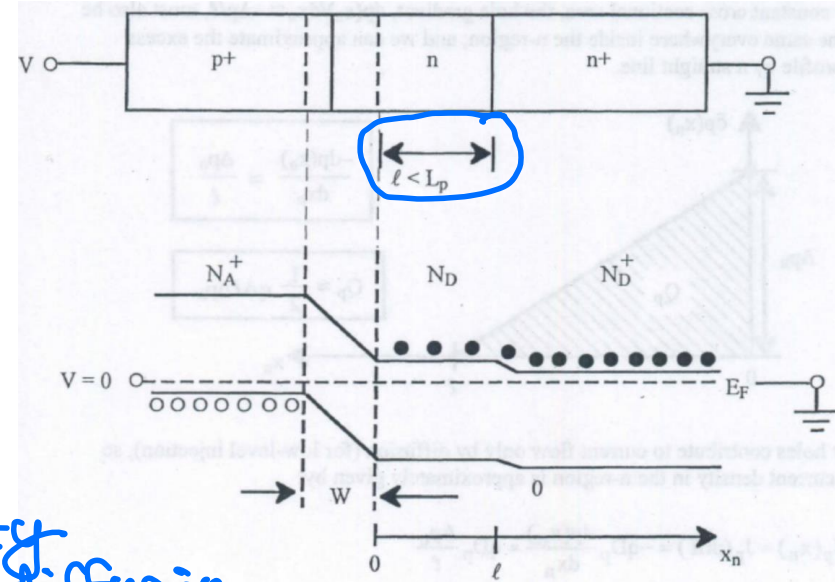
Narrow Base Diode

- Before we begin our discussion of BJTs, we need to discuss the narrow-base p-n diode
- The typical minority carrier diffusion length in Si is $\sim 10 \mu\text{m}$
- But modern device lengths are very small, on the order of $7-100 \text{ nm}$
- This can easily create situations where

$l < L_p$ or L_n \leftarrow minority carrier diffusion lengths
length of QNR

- Ex. Let's imagine we have a p^+-n diode with an n region width l less than the hole diffusion length
- This is called a narrow base diode

Special case of a BJT

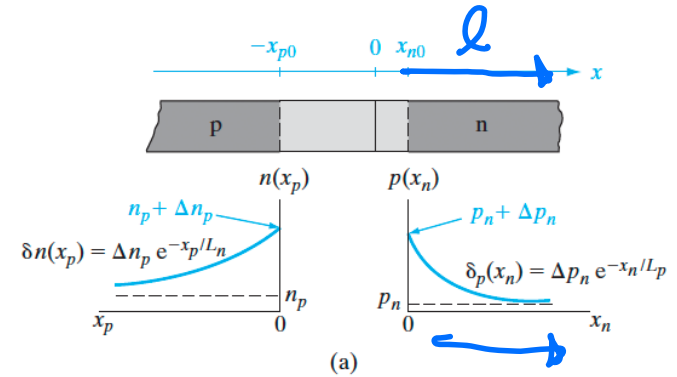


Excess Minority Carrier Spatial Distributions

- Recall our discussion on the long base diode (exponential decay):

$$\delta n(x_p) = \Delta n_p e^{-x_p/L_n} = n_p(e^{qV/kT} - 1)e^{-x_p/L_n}$$

$$\delta p(x_n) = \Delta p_n e^{-x_n/L_p} = p_n(e^{qV/kT} - 1)e^{-x_n/L_p}$$



- But instead of “long” ($l > L_p$) exponential decay:

$$\delta p(x) = \Delta p_{n0} e^{-x/L_p} = \frac{n_i^2}{N_d} \left(e^{qV/kT} - 1 \right) e^{-x/L_p}$$

- We have the “narrow” or “short” ($l < L_p$) approximation (straight line approximation):

$$\delta p(x) = \Delta p_{n0} \left(1 - \frac{x}{l} \right) = \frac{n_i^2}{N_d} \left(e^{qV/kT} - 1 \right) \left(1 - \frac{x}{l} \right)$$

- We can think of the (metal) contacts at the end of the p-n junction infinite sink.
Note the diode is too narrow (short) for any hole recombination in n-region, so recombination happens at the contact, setting the boundary conditions:

$$\delta p(x = l) = 0$$

$$\delta p(x = x_n) = \Delta p_n = p_n(e^{qV/kT} - 1)$$

At $x=0$, $\delta p = \Delta p_{n0}$
At $x=l$, $\delta p = 0$

Current in Narrow Base Diode

- Total injected (stored) minority charge at FB is the area under the triangle. Remember excess carrier distribution is a linear function of distance:

$$Q_p = \frac{1}{2} q \Delta p (Al) = \frac{1}{2} q Al \frac{n_i^2}{N_D} (e^{qV/kT} - 1)$$

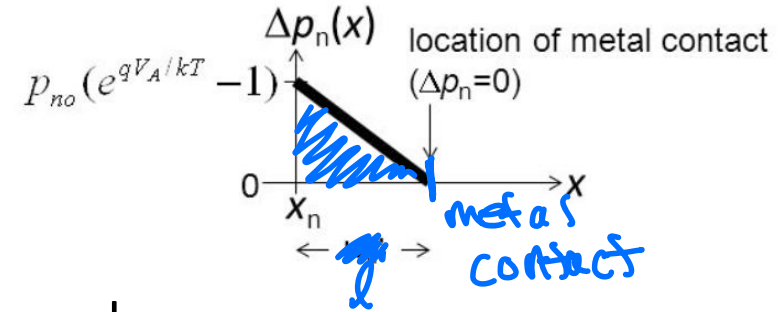
- The hole concentration gradient using the straight approximation: constant!

$$\frac{dp}{dx} = \frac{-\Delta p_n}{l}$$

- Assuming low-level injection, hole diffusion current can be written:

$$J_p = -q D_p \left(\frac{dp}{dx} \right) = +q D_p \frac{\Delta p_n}{l} = + \frac{q D_p}{l} \left(\frac{n_i^2}{N_D} \right) (e^{\frac{qV}{kT}} - 1)$$

- Compare with “long” diode diffusion current: $J_p = q \frac{D_p}{L_p} \frac{n_i^2}{N_D} (e^{qV/kT} - 1)$



Current in Narrow Base Diode

- l replace L_p in the denominator of the diode equation since $l \ll L_p$
- Because of constant gradient (slope), J_p is constant in narrow QNR because no holes are lost due to recombination as they diffuse to the metal contact!
- Shorter QNR \rightarrow steeper concentration gradient \rightarrow higher current in narrow base diode than "long" diode for the same voltage
- Total diode current if:
 - It's a p^+-n ($N_A \gg N_D$) diode: $J = J_p$
 - It's a $p-n$ ($N_A \sim N_D$) diode: $J = J_p + J_n$

